

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT7439143

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	RELEASE OF PATENT COLLATERAL
CONVEYING PARTY DATA	
Name	Execution Date
BANK OF AMERICA, N.A.	01/03/2022
RECEIVING PARTY DATA	
Name:	ANDROID INDUSTRIES, L.L.C.
Street Address:	2155 EXECUTIVE HILLS DR.
City:	AUBURN HILLS
State/Country:	MICHIGAN
Postal Code:	48326
PROPERTY NUMBERS Total: 2	
Property Type	Number
Application Number:	16274856
Application Number:	16279388
CORRESPONDENCE DATA	
Fax Number:	
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Email:	raymonda@millerjohnson.com
Correspondent Name:	MILLER JOHNSON
Address Line 1:	409 E JEFFERSON AVENUE, FIFTH FLOOR
Address Line 4:	DETROIT, MICHIGAN 48226
ATTORNEY DOCKET NUMBER:	18462-2
NAME OF SUBMITTER:	AILEEN RAYMOND
SIGNATURE:	/Aileen Raymond/
DATE SIGNED:	07/19/2022
Total Attachments: 3	
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RELEASE OF PATENT COLLATERAL

THIS RELEASE OF PATENT COLLATERAL (this "Release") is made as of January 3, 2022 by BANK OF AMERICA, N.A. ("Bank of America").

WITNESSETH:

WHEREAS, Android Industries, L.L.C. ("Android") executed that certain Loan and Security Agreement, dated as of December 5, 2017, and Android executed that certain Patent Security Agreement dated August 26, 2021 (together with the Loan and Security Agreement, as amended, restated, supplemented or otherwise modified from time to time, the "Amended Loan and Security Agreement"), in favor of Bank of America, pursuant to which the Android granted a security interest to Bank of America in certain patents and patent applications of Android; and

WHEREAS, in connection with the Amended Loan and Security Agreement, documentation was recorded with the United States Patent and Trademark Office at Reel 0809, Frame 044907 on December 12, 2017; and

WHEREAS, Bank of America has agreed to release all of its liens on the patents, patent applications and inventions of the Android identified on Exhibit A attached hereto and made a part hereof (the "Released Collateral"), and to reconvey any and all rights in the Released Collateral to the persons legally entitled thereto.

NOW, THEREFORE, in consideration of the promises and other good and valuable consideration, receipt of which is hereby acknowledged, Bank of America hereby terminates, fully discharges, and irrevocably releases any and all of its liens and security interests in and to the Released Collateral.

Bank of America hereby agrees to take all further actions, and provide to Android and its successors, assigns and legal representatives all such cooperation and assistance, including, without limitation, the execution and delivery of any and all further documents or other instruments, as Android and its successors, assigns and legal representatives may reasonably request in order to confirm, effectuate or record this Release.

The individual executing this Release warrants that they have the power and authority to execute this Release. Facsimile signatures of this Release, including those sent in .pdf format by email, will be treated as originals for all purposes.

[Signature page follows]

IN WITNESS WHEREOF, Bank of America has executed this Release as the date first set forth above.

BANK OF AMERICA, N.A.

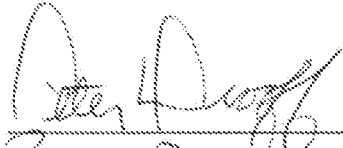
By: 
Name: PETER DROZDY
Its: SVP

Exhibit A

Country	Title	App. Date	App. No.	Pub. Date	Pub. No.
US	Tire Preparation for Adhesive Using Laser Ablation System and Method	2018-02-14	16/274,856	2019-08-15	US20190248084A1
CN	Tire Preparation for Adhesive Using Laser Ablation System and Method	2019-02-14	CN201980012907.0A	2020-09-25	CN111712389A
EU	Tire Preparation for Adhesive Using Laser Ablation System and Method	2019-02-14	EP19754287.1A	2020-12-23	EP3752374
US	Tire Sensor Installation System And Method	2019-02-19	16/279,388	2021-05-04	10,994,494B2
CN	Tire Sensor Installation System And Method	2019-02-19	CN201980014067.1A	2020-10-02	CN111741860A
EU	Tire Sensor Installation System And Method	2019-02-19	EP19754220.2A	2020-12-30	EP3755351A1